

Title (en)
METHOD AND APPARATUS FOR DESIGNING A BENDING MOLD FOR GLASS SHEETS USING A 3-DIMENSIONAL CAD-APPLICATION FOR SOLID MODELS

Title (de)
VERFAHREN UND VORRICHTUNG ZUM ENTWURF EINER BIEGEFORM FÜR GLASSCHEIBEN MITTELS EINES 3-DIMENSIONALEN CAD-SYSTEMS FÜR FESTKÖRPERMODELLE

Title (fr)
CONCEPTION D'UN MOULE FLEXIBLE DESTINE A UNE PLAQUE VITREE AU MOYEN D'UNE APPLICATION CAO TRIDIMENSIONNELLE POUR MODELES SOLIDES

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Application
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Abstract (en)
[origin: WO03004424A2] The present invention aims at providing a method for designing a glass-plate-aimed bending mold making use of a 3-dimensional CAD application for solid models, in a short time with simple operations, by utilizing a previously designed solid model. To this end, there is modified a ring frame of a solid model of a mold stored in an existing-solid-model storing part, such that the ring frame conforms to the shape of a new glass plate, by glass shape replacing means. By using modified parameter reflecting means, the modification of the modifiable parameters inherited from the existing solid-model is reflected to the modified solid model, to thereby optimize the modifiable parameters of a new solid model.

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